## **BOARD CHARACTERISTICS**

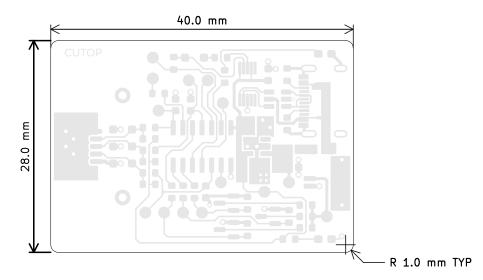
1.6000 mm Copper Layer Count: Board Thickness:

Board overall dimensions: 40.0000 mm x 28.0000 mm

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.3000 mm

Copper Finish: HAL lead-free Impedance Control: No Castellated pads: Plated Board Edge: No No

Edge card connectors: No



Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Direct Printing	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.01 mm	Black	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	FR4 natural	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.01 mm	Black	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Direct Printing	0 mm	White	1	0

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## POUNAMU ELECTRONICS

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1116		W L_		

Size: A4 Date: 08-07-2025 Rev: B KiCad E.D.A. 8.0.8 ld: 1/1

